

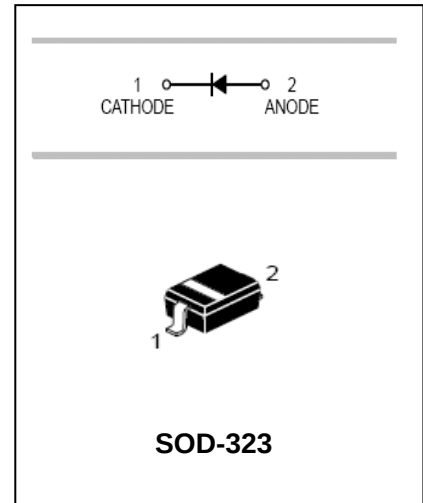
High Speed Switching Diodes

TMMDL914

FEATURES

- Small Surface Mounting Type: SOD-323
- High Speed $t_{rr} = 4.0\text{ns(Typ.)}$
- Halogen free
- Qualified to AEC-Q101 Standards for High Reliability.

HF



APPLICATIONS

- High speed switching

ORDERING INFORMATION

Type No.	Marking	Package Code
TMMDL914	5D	SOD-323

MAXIMUM RATING @ $T_a=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Limits	Unit
Reverse Voltage	V_R	100	V
Forward Current	I_F	200	mA
Peak forward surge current	$I_{FM(surge)}$	500	mA
Power Dissipation	P_D	200	mW
Thermal resistance junction to ambient air	$R_{\theta JA}$	635	$^\circ\text{C/W}$
Thermal resistance junction to Lead	$R_{\theta JL}$	626	$^\circ\text{C/W}$
Thermal resistance junction to Case	$R_{\theta JC}$	356	$^\circ\text{C/W}$
Junction temperature	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature	T_{STG}	-55 to +150	$^\circ\text{C}$

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ELECTRICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Reverse breakdown voltage	$V_{(BR)}$	100			V	$I_R = 100\mu\text{A}$
Forward voltage	V_F			1.0	V	$I_F = 10\text{mA}$
Reverse current	I_R			25 5.0	nA μA	$V_R = 20\text{V}$ $V_R = 75\text{V}$
Capacitance between terminals	C_T			4.0	pF	$V_R = 0\text{V}$, $f = 1.0\text{MHz}$
Reverse Recovery Time	t_{rr}			4	ns	$I_F = I_R = 10\text{mA}$

TYPICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified

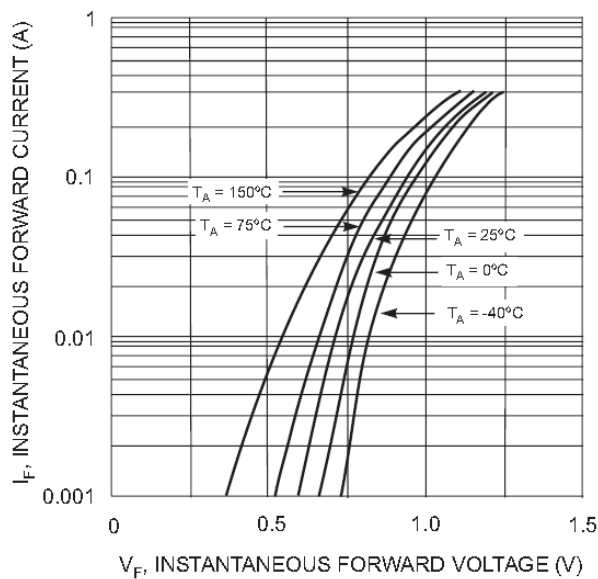


Fig. 1 Forward Characteristics

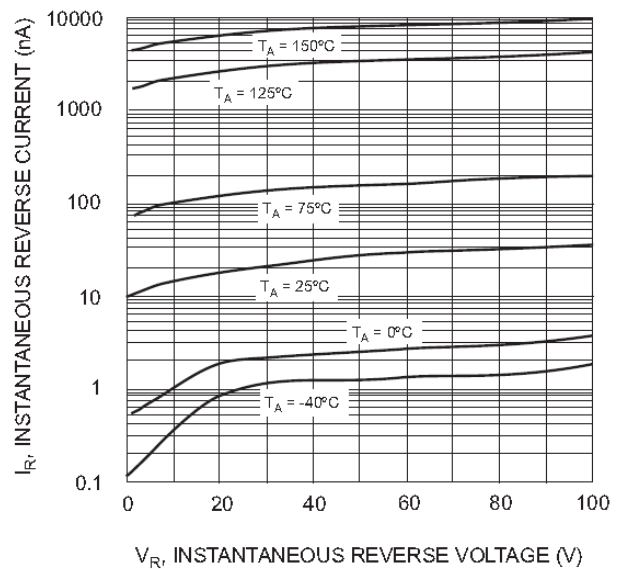


Fig. 2 Typical Reverse Characteristics

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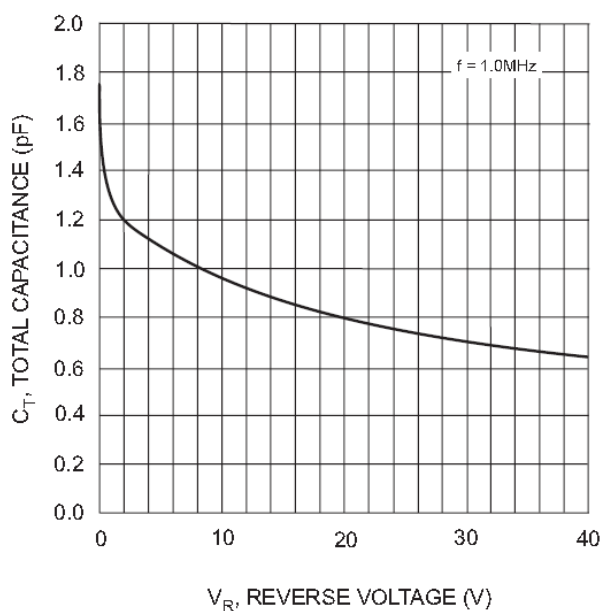


Fig. 3 Typical Capacitance vs. Reverse Voltage

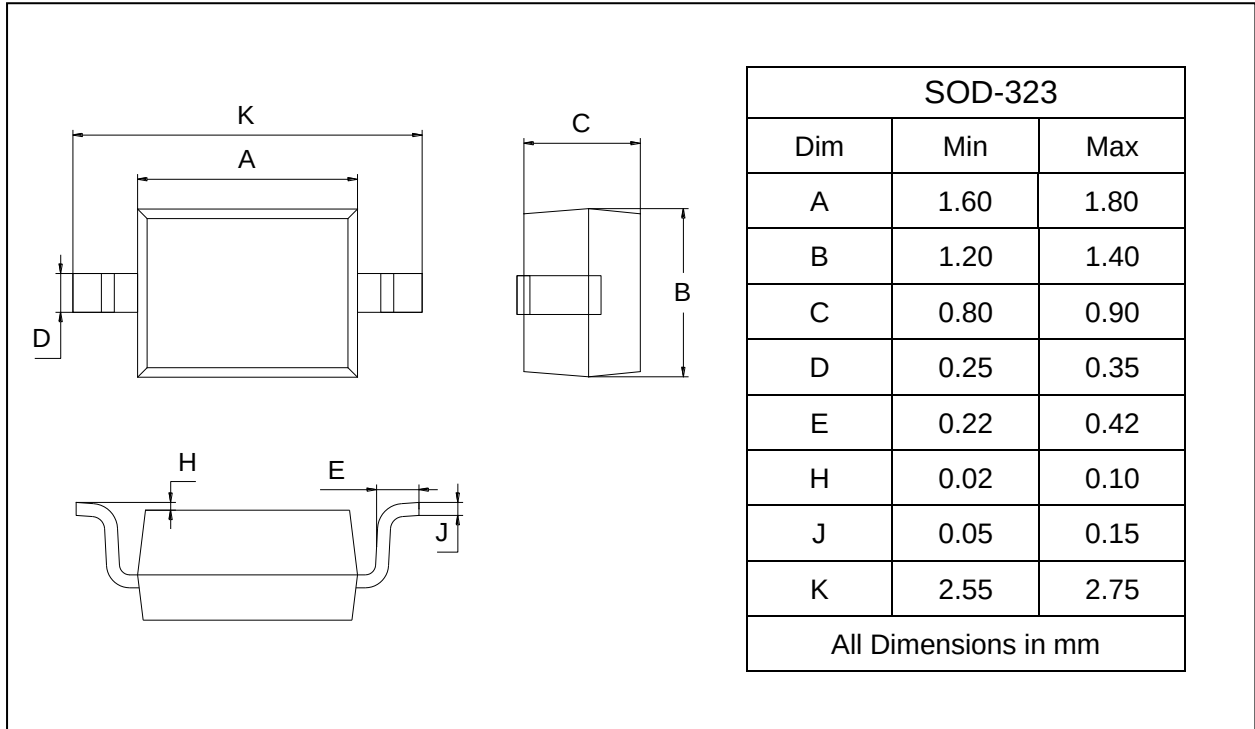
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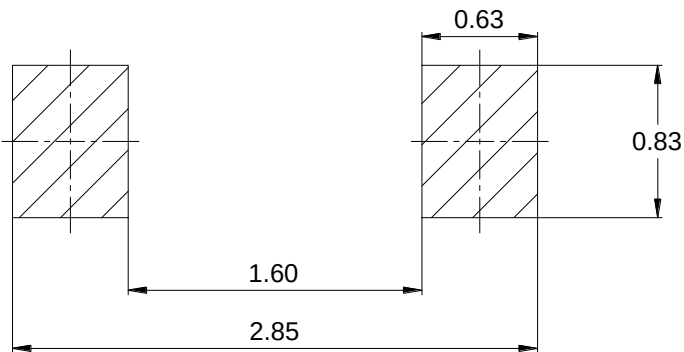
PACKAGE OUTLINE

Plastic surface mounted package

SOD-323



SOLDERING FOOTPRINT



Unit: mm

PACKAGE INFORMATION

Device	Package	Shipping
TMMDL914	SOD-323	3000 pcs / Tape & Reel